

ESD NOISE CLIPPING DIODE NNCD6.8RG

LOW CAPACITANCE TYPE ELECTROSTATIC DISCHARGE NOISE CLIPPING DIODE (QUARTO TYPE: COMMON ANODE) 5-PIN MINI MOLD

DESCRIPTION

The NNCD6.8RG is a low capacitance type diode developed for ESD (Electrostatic Discharge) absorption. Based on the IEC61000-4-2 test on electromagnetic interference (EMI), the diode assures an endurance of no less than 8 kV, and capacitance is small with 10 pF between the terminal. This product series is the most suitable for ESD absorption in the high-speed data communication bus such as USB.

With four elements mounted in the 5-PIN mini mold package, the product can cope with more high density assembling.

FEATURES

- Base on the electrostatic discharge immunity test (IEC 61000-4-2), the product assures the minimum endurance of 8 kV.
- Capacitance: 10 pF (at $V_R = 0$ V, $f = 1$ MHz) between the terminal. The low capacitance can realize the excellent frequency characteristic.
- With four elements in the mini mold package, the products can achieve high density and automatic packaging.

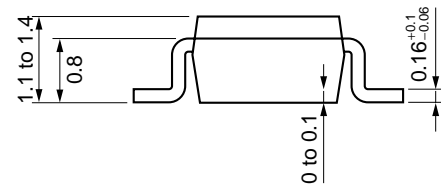
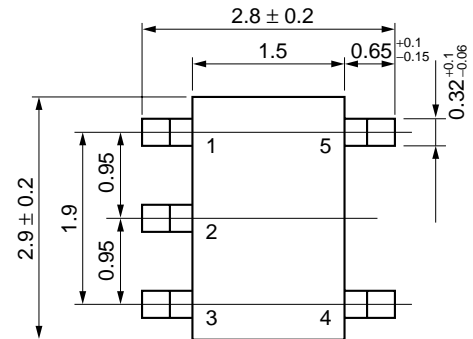
APPLICATIONS

- External interface circuit ESD absorption in the high-speed data communication bus such as USB.

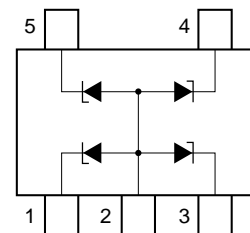
MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Item	Symbol	Rating	Unit	Remark
Power Dissipation	P	200	mW	Total
Surge Reverse Power	P_{RSM}	2 ($t = 10 \mu\text{s}$ 1 pulse)	W	
Junction Temperature	T_j	150	$^\circ\text{C}$	
Storage Temperature	T_{stg}	-55 to +150	$^\circ\text{C}$	

PACKAGE DIMENSION (Unit: mm)



ELECTRODE CONNECTION



- 1 : K1 Cathode 1
- 2 : A Anode (common)
- 3 : K2 Cathode 2
- 4 : K3 Cathode 3
- 5 : K4 Cathode 4

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ELECTRICAL CHARACTERISTICS (T_A = 25 °C (A to K1, A to K2, A to K3, A to K4))

TYPE No.	Breakdown Voltage ^{Note 1} V _{BR} (V)			Capacitance C _t (pF)		Reverse Leakage I _R (μA)		Dynamic Impedance ^{Note 2} Z _z (Ω)		ESD Voltage ^{Note 3} (kV)	
	MIN.	MAX.	I _T (mA)	TYP.	Condition	MAX.	V _R (V)	MAX.	I _T (mA)	MIN.	Condition
NNCD6.8RG	6.2	7.1	5	10	V _R = 0 V f = 1 MHz	2	3.5	40	5	8	C = 150 pF R = 330 Ω Contact discharge

Notes 1. tested with pulse (40 ms)

2. Z_z is measured at I_T given a small A.C. signal.

3. Biased upon with IEC 61000-4-2

TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

Figure 1. POWER DISSIPATION vs. AMBIENT TEMPERATURE

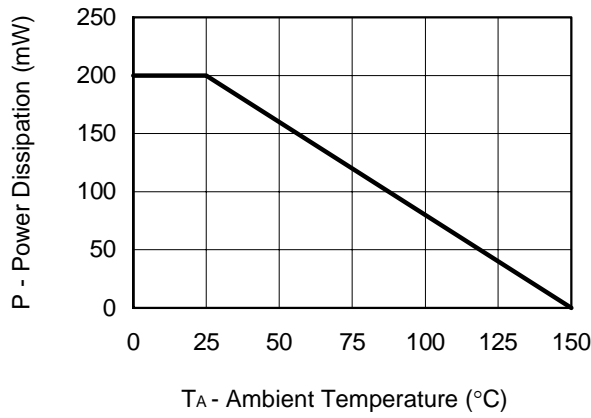


Figure 2. I_T - V_{BR} CHARACTERISTICS (A-K1, A-K2, A-K3, A-K4)

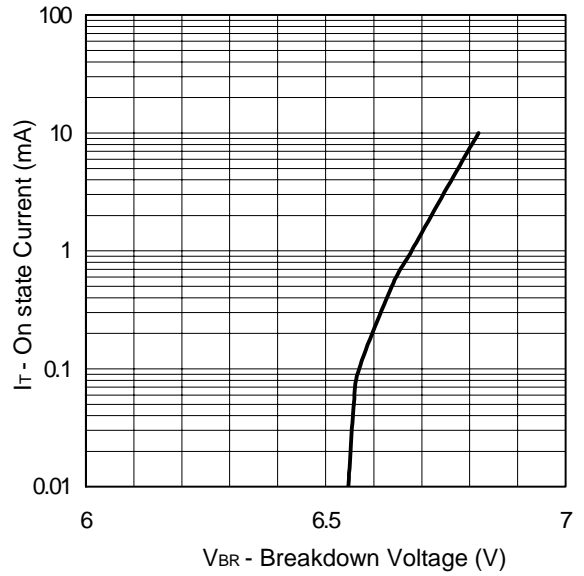


Figure 3. Z_z - I_T

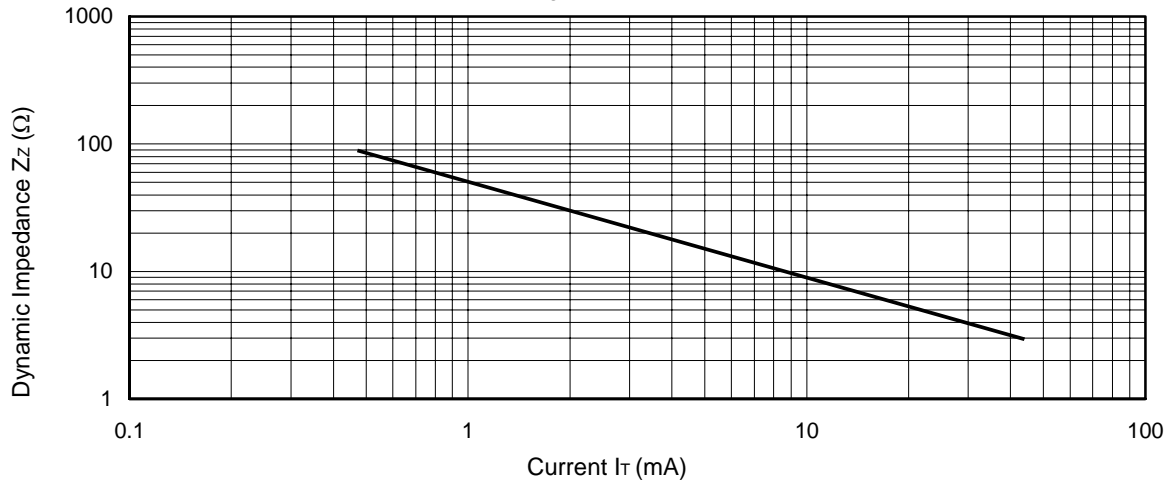


Figure 4. C_T - V_R CHARACTERISTICS

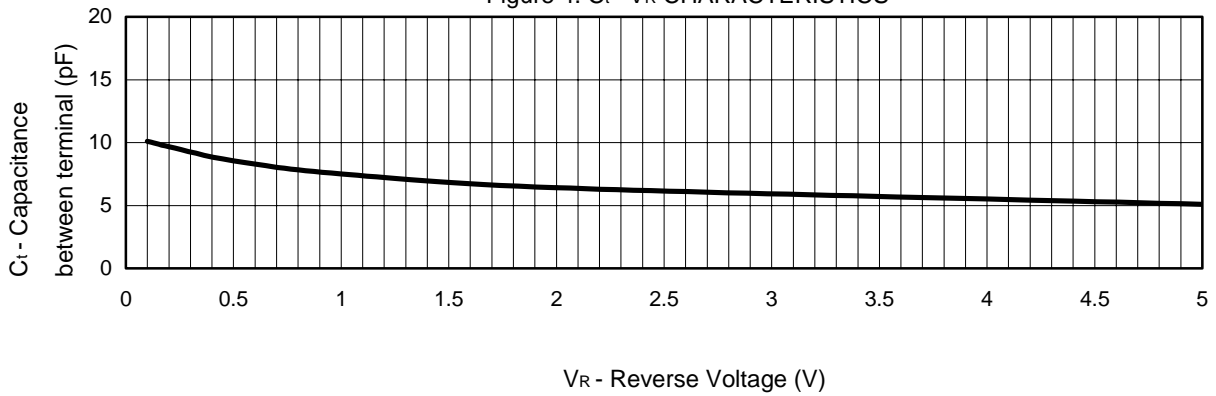
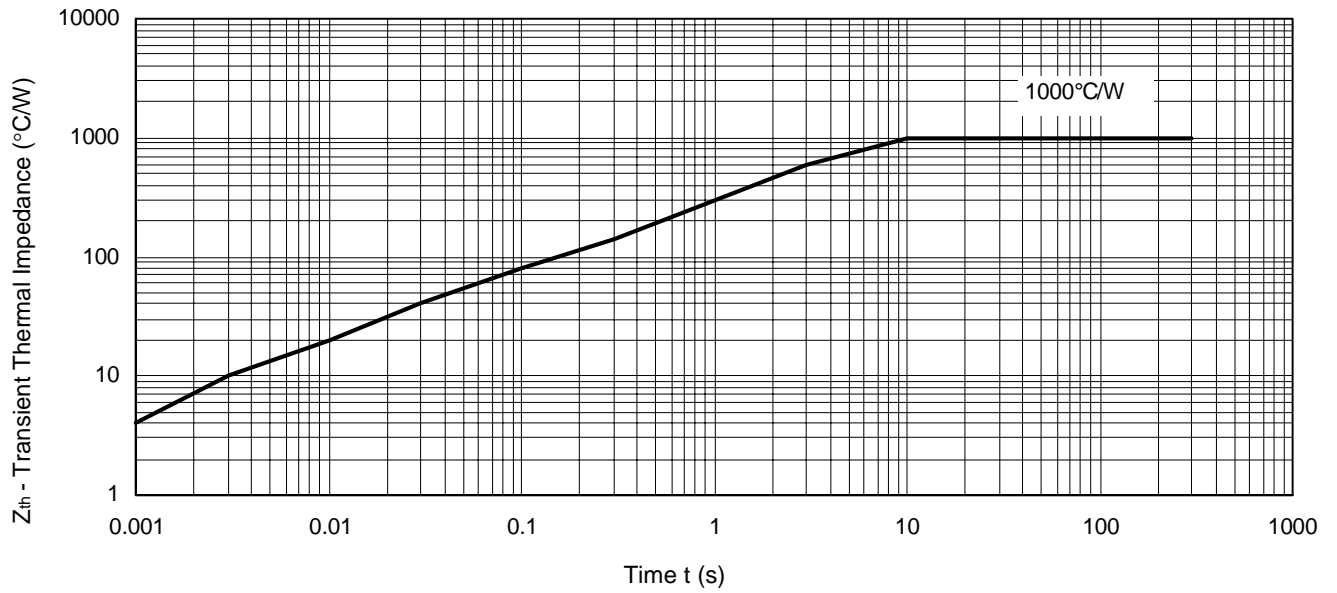
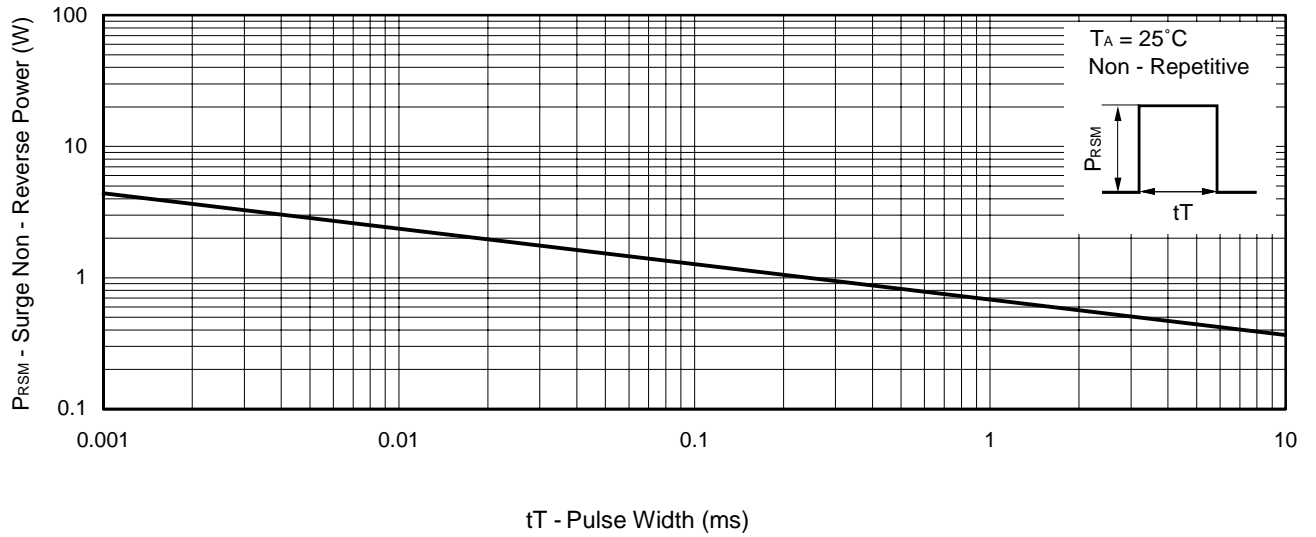


Figure 5. TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS



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Figure 6. SURGE REVERSE POWER RATINGS



[MEMO]

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